



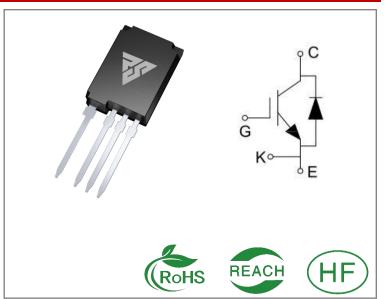
IF	V _{ce} (sat)	VCES
120A	1.69V	1200V

Applications:

- Energy storage inverter
- Uninterruptible Power Supply (UPS)
- Solar Inverter

Features:

- 1200V trench gate/field termination process
- Very low Vce(sat)
- Low switching loss
- Positive temperature coefficient in Vce(sat)



Ordering Information

Part Number	Package	Marking	Packing	Qty.
RSG120N120HZP	T0-247plus-4	RSG120N120HZP	Tube	30 PCS

Absolute Maximun Ratings Tc= 25°C unless otherwise specified

Symbol	Parameter	RSG120N120HZP	Units
VCES	Collector-Emitter Voltage	1200	V
VGES	Gate- Emitter Voltage	±20	V
IC	Continuous DC collector current TC = 100 °C	120	Α
ICrm	Repetitive peak collector current tp=1 ms	360	Α
Ptot	Total Power Dissipation @ TC = 25°C	1250	W
Tstg	Operating Junction and Storage Temperature Range	-40to150	°C
TL	Maximum Temperature for Soldering	260	°C

Thermal Characteristic

Symbol	Parameter	RSG120N120HZP	Units
R _{thJC}	Thermal Resistance, Junction to case for IGBT	0.12	K/W



Electrical Characteristics (Tc=25°C unless otherwise noted)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test C	onditions
Static Cha	nracteristics						
V(BR)CES	Collector-Emitter Breakdown Voltage	1200	-		V	V _{GE} =0V,I	_{CE} =0.25mA
ICES	Collector-Emitter Leakage Current	-	-	1	mA	V _{GE} = 0	0V, .200V
IGES	Gate to Emitter Leakage current	-	-	200	nA	V _{GE} =+	
VCE(sat)	Collector-Emitter Saturation Voltage	-	1.69	2.1	٧	I _C =120	T _j =25°
	Gate Threshold Voltage	-	2.25		V	V _{GE} =15	T _j =175°
VGE(th)	Collector-Emitter Breakdown Voltage	5.0	5.6	6.2	V	I _C =2.3mA	A,V _{CE} =V _{GE}
Gfs	Transconductance		106		S	I _C =120A,	V _{CE} =20V
Dynamic (Characteristics						
Cies	Input Capacitance	-	16800			.,,	05)/
Coes	Output Capacitance	-	408		PF		=25V, _E =0V,
Cres	Reverse Transfer Capacitance	-	126		-	f=1	00KHz
Qg	Total Gate Charge		1025		uC	IC = 120.	A, VGE = E =960 V
Switching	Characteristics						
td(ON)	Turn-on Delay Time	-	205				
t _r	Rise Time	-	115		ns	V _{CE} =600	V,
td(OFF)	Turn-Off Delay Time	-	150		1	I _C =120A,	
t _f	Fall Time	-	72		1	V _{GE} =+/-1	.5V,
Eon	Turn-On Switching Loss	-	12.5		_	R_g =20 Ω , Inductive	Joad
E _{off}	Turn-Off Switching Loss	-	4.2		- mJ	inductive	: LUdU



Diode Maximum Ratings (TJ= 25 °C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
VRRM	Repetitive Peak Reverse Voltage	1200	V	TC = 25℃
IF	Forward Current	120	Α	TC = 100°C
IFRM	Repetitive Peak Forward Surge Current	360	Α	tp=1 ms

Characteristics Values (T_C=25°C unless otherwise noted)

Symbol	Parameter	Min.	Тур.	Max.	Test Conditions	Unit
VF	Forward Voltage		2.1	2.6	IF =120A,V _{GE} =0V TJ = 25℃	V
			1.85		IF =120A,V _{GE} =0V TJ = 175℃	
IRM	Peak reverse recovery		35		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 25°C	A
IKIVI	current		81		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 175°C	A
Orr	Reverse Recovery		7		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 25°C	uC
Qrr	Charge		24		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 175°C	uC
	Davidea Davidea timo		425		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 25°C	
trr	Reverse Recovery time		720		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 175°C	ns
F	Reverse recovered		2.4		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 25℃	1
Erec	energy		9.2		VR = 600V, IF =120A,V _{GE} =-15V diF/dt=700A/us TJ = 175°C	mJ
R _{thJC}	Diode Thermal Resistance, Junction		0.22			K/W
Tvj op	Temperature under switching conditions	-40		175		°C



Typical Feature Curve

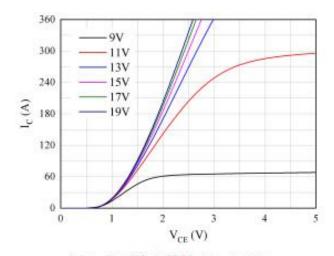


图 1. 典型输出特性 (T_{vj}=25℃)

Figure 1. Typical output characteristics (Tvj=25°C)

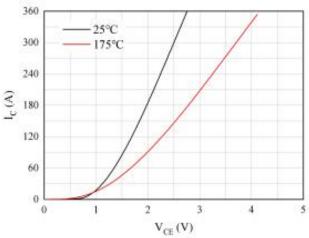


图 3. 典型输出特性 (VGE=15V)

Figure 3. Typical output characteristics (V_{GE}=15V)

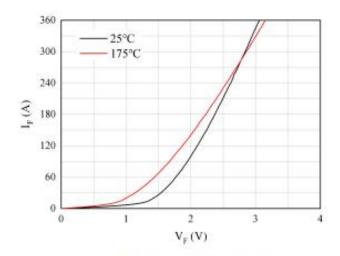


图 5. 正向偏压特性 二极管

Figure 5. Forward characteristic of Diode

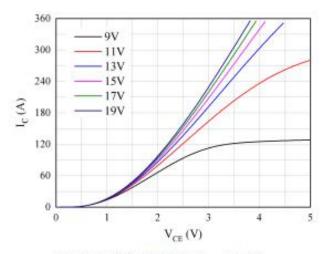


图 2. 典型输出特性 (Tvi=175°C)

Figure 2. Typical output characteristics (T_{vj}=175°C)

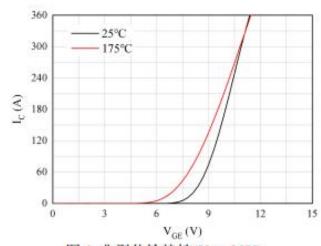


图 4. 典型传输特性(Vce=20V)

Figure 4. Typical transfer characteristic (V_{CE}=20V)

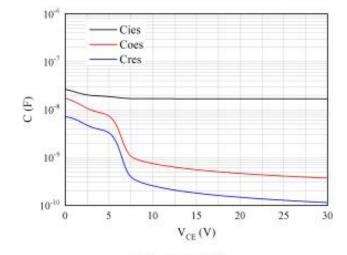


图 6. 电容特性

Figure 6. Capacitance characteristic



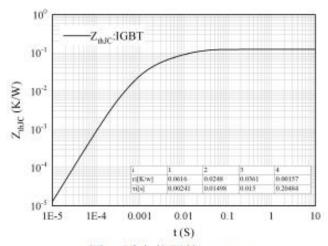


图 7. 瞬态热阻抗 IGBT

Figure 7. Transient thermal impedance IGBT, $Z_{th, C}=f(t)$

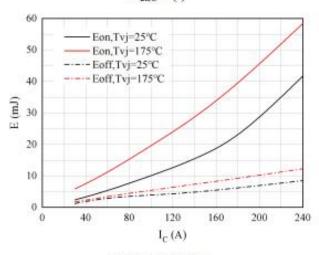


图 9. 开关损耗

Figure 9. Switching losses of IGBT Var=±15V, Rgon=200, Rgoff=200, Var=600V

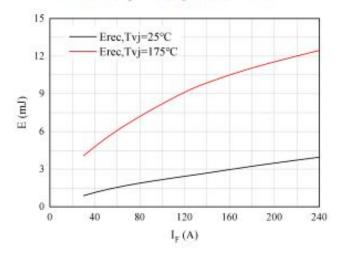


图 11. 开关损耗 二极管

Figure 11. Switching losses of Diode Rgon=20Ω, V_{CE}=600V

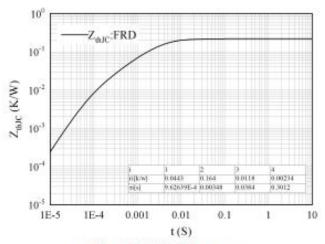


图 8. 瞬态热阻抗 FRD

Figure 8. Transient thermal impedance FRD, $Z_{th/C}=f(t)$

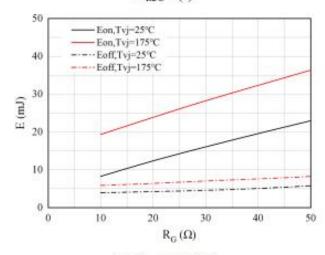


图 10. 开关损耗

Figure 10. Switching losses of IGBT Vgs=±15V, Ic=120A, Vcs=600V

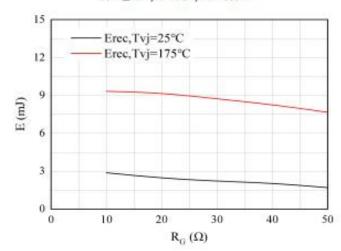
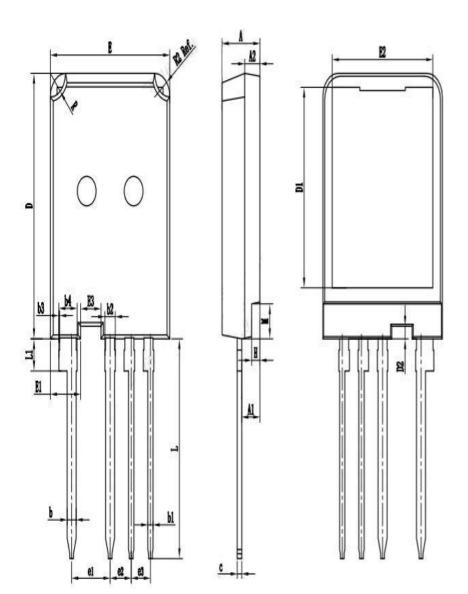


图 12. 开关损耗 二极管

Figure 12. Switching losses of Diode



Package outline drawing(TO-247PLUS-4 Unit: mm)



Symbol	Dimensions In Millimeters				
Symbol	Min	Max 5.100			
Α	4.900				
A1	2.310	2.510			
A2	1.900	2.100			
b	1.160	1.290			
b1	0.650	0.790			
b2	1.360	1.490			
b3	0.000	0.200			
b4	2.160	2.290			
С	0.590	0.660			
D	22.300	22.500			
D1	16.650	17.250			
D2	1.000	1.100			
E	15.700	15.900			
E1	3.900	4.100			
E2	13.100	13.500			
E3	2.580	2.780			
e1	5.080	BSC			
e2	2.790	BSC			
e3	2.540 BSC				
Н	1.000	1.200			
L	18.460	18.660			
L1	2.620	2.820			
M	2.850	3.050			
R	1.900	2.100			



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